



**Advanced Power
Electronics Corp.**

AP2626GY-HF

Halogen-Free Product

N-CHANNEL ENHANCEMENT MODE

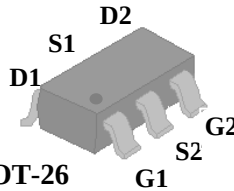
POWER MOSFET

▼ Simple Drive Requirement

▼ Smaller Outline Package

▼ Surface mount package

▼ RoHS Compliant & Halogen-Free SOT-26

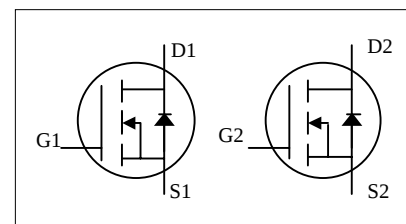


BV_{DSS}	30V
$R_{DS(ON)}$	72m Ω
I_D	3.3A

Description

AP2626 series are from Advanced Power innovated design and silicon process technology to achieve the lowest possible on-resistance and fast switching performance. It provides the designer with an extreme efficient device for use in a wide range of power applications.

The SOT-26 package is widely used for all commercial-industrial applications.



Absolute Maximum Ratings@ $T_J=25^\circ\text{C}$ (unless otherwise specified)

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	30	V
V_{GS}	Gate-Source Voltage	+20	V
$I_D@T_A=25^\circ\text{C}$	Drain Current ³ , V_{GS} @ 10V	3.3	A
$I_D@T_A=70^\circ\text{C}$	Drain Current ³ , V_{GS} @ 10V	2.6	A
I_{DM}	Pulsed Drain Current ¹	10	A
$P_D@T_A=25^\circ\text{C}$	Total Power Dissipation	1.2	W
	Linear Derating Factor	0.01	W/ $^\circ\text{C}$
T_{STG}	Storage Temperature Range	-55 to 150	$^\circ\text{C}$
T_J	Operating Junction Temperature Range	-55 to 150	$^\circ\text{C}$

Thermal Data

Symbol	Parameter	Value	Unit
Rthj-a	Maximum Thermal Resistance, Junction-ambient ³	110	$^\circ\text{C}/\text{W}$



AP2626GY-HF

Electrical Characteristics@T_j=25°C(unless otherwise specified)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250uA	30	-	-	V
ΔBV _{DSS} /ΔT _j	Breakdown Voltage Temperature Coefficient	Reference to 25°C, I _D =1mA	-	0.03	-	V/°C
R _{DS(ON)}	Static Drain-Source On-Resistance ²	V _{GS} =10V, I _D =3A	-	-	72	mΩ
		V _{GS} =4.5V, I _D =2A	-	-	120	mΩ
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250uA	1	-	3	V
g _{fs}	Forward Transconductance	V _{DS} =5V, I _D =3A	-	2.8	-	S
I _{DSS}	Drain-Source Leakage Current	V _{DS} =30V, V _{GS} =0V	-	-	1	uA
	Drain-Source Leakage Current (T _j =70°C)	V _{DS} =24V, V _{GS} =0V	-	-	25	uA
I _{GSS}	Gate-Source Leakage	V _{GS} =±20V, V _{DS} =0V	-	-	±100	nA
Q _g	Total Gate Charge	I _D =3A	-	3.2	5.1	nC
Q _{gs}	Gate-Source Charge	V _{DS} =25V	-	0.9	-	nC
Q _{gd}	Gate-Drain ("Miller") Charge	V _{GS} =4.5V	-	1.7	-	nC
t _{d(on)}	Turn-on Delay Time	V _{DS} =15V	-	3.7	-	ns
t _r	Rise Time	I _D =1A	-	10.1	-	ns
t _{d(off)}	Turn-off Delay Time	R _G =3.3Ω	-	11.8	-	ns
t _f	Fall Time	V _{GS} =10V	-	2.3	-	ns
C _{iss}	Input Capacitance	V _{GS} =0V	-	170	270	pF
C _{oss}	Output Capacitance	V _{DS} =25V	-	50	-	pF
C _{rss}	Reverse Transfer Capacitance	f=1.0MHz	-	35	-	pF
R _g	Gate Resistance	f=1.0MHz	-	1.2	-	Ω

Source-Drain Diode

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
V _{SD}	Forward On Voltage ²	I _S =1A, V _{GS} =0V	-	-	1.2	V
t _{rr}	Reverse Recovery Time	I _S =3A, V _{GS} =0V,	-	15	-	ns
Q _{rr}	Reverse Recovery Charge	dI/dt=100A/μs	-	8	-	nC

Notes:

- 1.Pulse width limited by Max. junction temperature.
- 2.Pulse test
- 3.Surface mounted on 1 in² copper pad of FR4 board, t ≤5sec ;180°C/W when mounted on min. copper pad.

THIS PRODUCT IS SENSITIVE TO ELECTROSTATIC DISCHARGE, PLEASE HANDLE WITH CAUTION.

USE OF THIS PRODUCT AS A CRITICAL COMPONENT IN LIFE SUPPORT OR OTHER SIMILAR SYSTEMS IS NOT AUTHORIZED.

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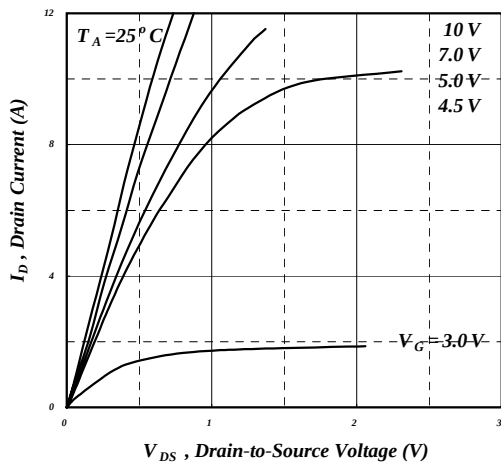


Fig 1. Typical Output Characteristics

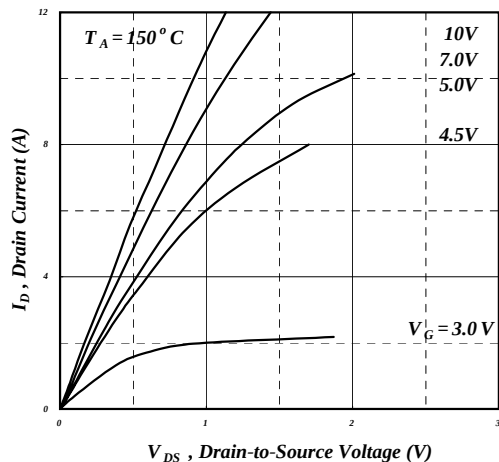


Fig 2. Typical Output Characteristics

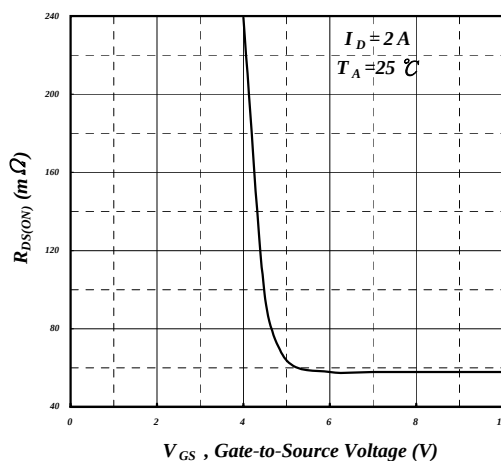


Fig 3. On-Resistance v.s. Gate Voltage

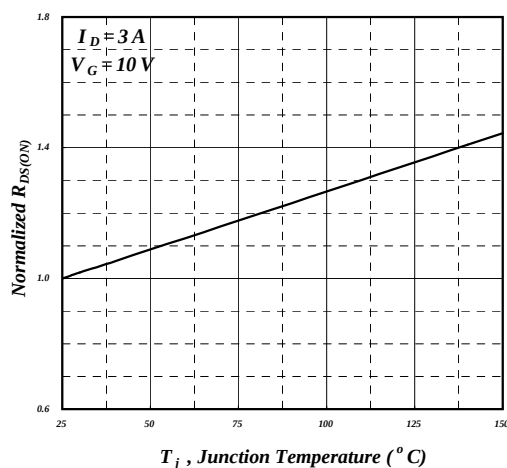


Fig 4. Normalized On-Resistance v.s. Junction Temperature

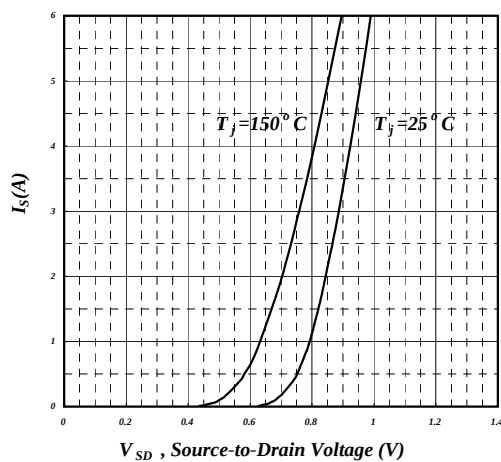


Fig 5. Forward Characteristic of Reverse Diode

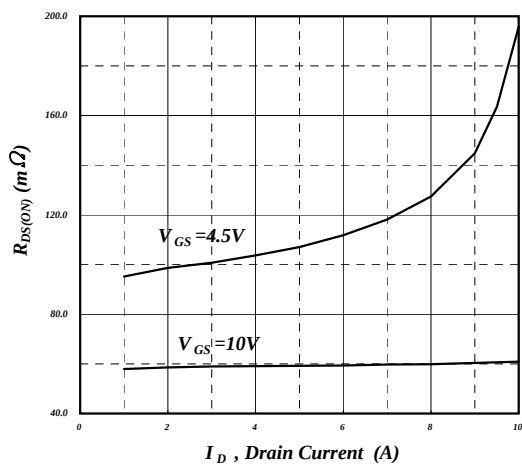


Fig 6. On-Resistance vs. Drain Current

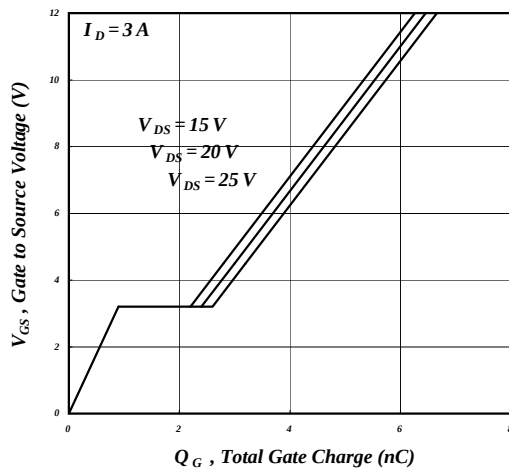


Fig 7. Gate Charge Characteristics

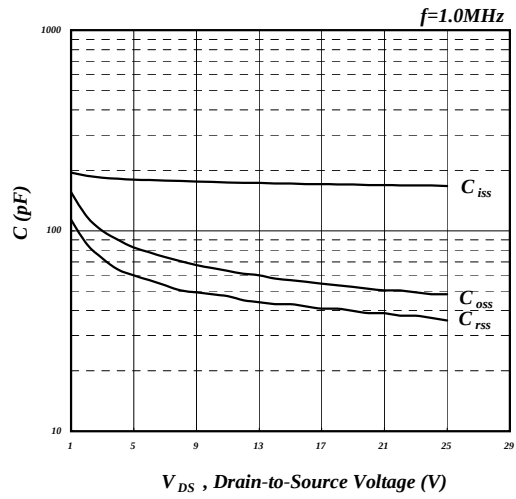


Fig 8. Typical Capacitance Characteristics

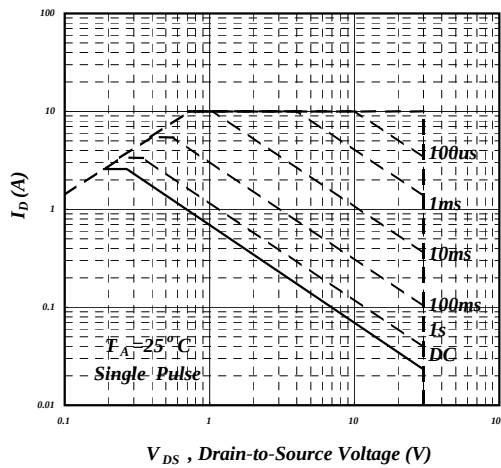


Fig 9. Maximum Safe Operating Area

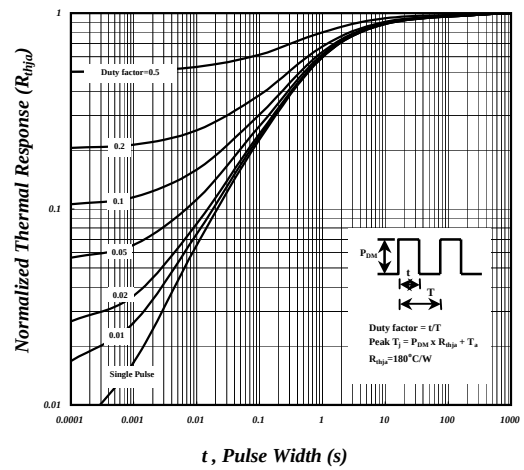


Fig 10. Effective Transient Thermal Impedance

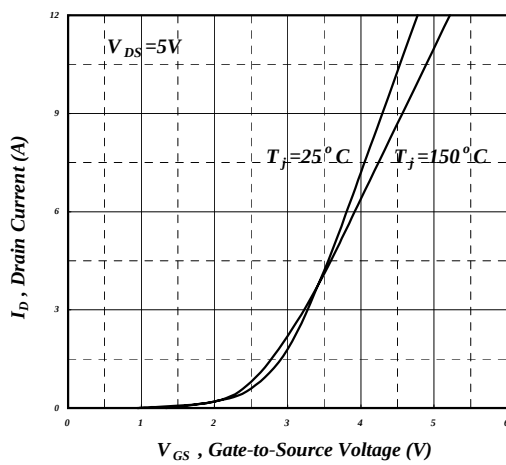


Fig 11. Transfer Characteristics



Fig 12. Gate Charge Waveform



MARKING INFORMATION

